

**NPN-Silizium-Fototransistor**  
**Silicon NPN Phototransistor**  
**Lead (Pb) Free Product - RoHS Compliant**

**BPX 38**



**Wesentliche Merkmale**

- Speziell geeignet für Anwendungen im Bereich von 450 nm bis 1120 nm
- Hohe Linearität
- Hermetisch dichte Metallbauform (TO-18) mit Basisanschluß, geeignet bis 125 °C
- Gruppiert lieferbar

**Anwendungen**

- Lichtschranken für Gleich- und Wechsellichtbetrieb
- Industrieelektronik
- „Messen/Steuern/Regeln“

**Features**

- Especially suitable for applications from 450 nm to 1120 nm
- High linearity
- Hermetically sealed metal package (TO-18) with base connection, suitable up to 125 °C
- Available in groups

**Applications**

- Photointerrupters
- Industrial electronics
- For control and drive circuits

<b>Typ Type</b>	<b>Bestellnummer Ordering Code</b>
BPX 38	Q62702P0015
BPX 38-2/3	Q62702P3578
BPX 38-3	Q62702P0015S003
BPX 38-4	Q62702P0015S004

**Grenzwerte****Maximum Ratings**

<b>Bezeichnung Parameter</b>	<b>Symbol Symbol</b>	<b>Wert Value</b>	<b>Einheit Unit</b>
Betriebs- und Lagertemperatur Operating and storage temperature range	$T_{op}; T_{stg}$	- 40 ... + 125	°C
Kollektor-Emitterspannung Collector-emitter voltage	$V_{CE}$	50	V
Kollektorstrom Collector current	$I_C$	50	mA
Kollektorspitzenstrom, $\tau < 10 \mu\text{s}$ Collector surge current	$I_{CS}$	200	mA
Emitter-Basisspannung Emitter-base voltage	$V_{EB}$	7	V
Verlustleistung, $T_A = 25 \text{ }^\circ\text{C}$ Total power dissipation	$P_{tot}$	220	mW
Wärmewiderstand Thermal resistance	$R_{thJA}$	450	K/W

**Kennwerte ( $T_A = 25^\circ\text{C}$ ,  $\lambda = 950 \text{ nm}$ )**

**Characteristics**

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Wellenlänge der max. Fotoempfindlichkeit Wavelength of max. sensitivity	$\lambda_{S \max}$	880	nm
Spektraler Bereich der Fotoempfindlichkeit $S = 10\%$ von $S_{\max}$ Spectral range of sensitivity $S = 10\%$ of $S_{\max}$	$\lambda$	450 ... 1120	nm
Bestrahlungsempfindliche Fläche Radiant sensitive area	$A$	0.675	$\text{mm}^2$
Abmessung der Chipfläche Dimensions of chip area	$L \times B$ $L \times W$	1 × 1	$\text{mm} \times \text{mm}$
Halbwinkel Half angle	$\phi$	$\pm 40$	Grad deg.
Fotostrom der Kollektor-Basis-Fotodiode Photocurrent of collector-base photodiode $E_e = 0.5 \text{ mW/cm}^2$ , $V_{CB} = 5 \text{ V}$ $E_v = 1000 \text{ lx}$ , Normlicht/standard light A, $V_{CB} = 5 \text{ V}$	$I_{PCB}$ $I_{PCB}$	1.8 5.5	$\mu\text{A}$ $\mu\text{A}$
Kapazität Capacitance $V_{CE} = 0 \text{ V}$ , $f = 1 \text{ MHz}$ , $E = 0$ $V_{CB} = 0 \text{ V}$ , $f = 1 \text{ MHz}$ , $E = 0$ $V_{EB} = 0 \text{ V}$ , $f = 1 \text{ MHz}$ , $E = 0$	$C_{CE}$ $C_{CB}$ $C_{EB}$	23 39 47	pF pF pF
Dunkelstrom Dark current $V_{CE} = 25 \text{ V}$ , $E = 0$	$I_{CEO}$	20 ( $\leq 100$ )	nA

**Die Fototransistoren werden nach ihrer Fotoempfindlichkeit gruppiert und mit arabischen Ziffern gekennzeichnet.**

**The phototransistors are grouped according to their spectral sensitivity and distinguished by arabian figures.**

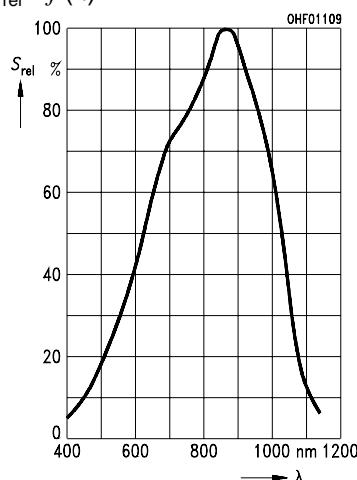
<b>Bezeichnung Parameter</b>	<b>Symbol Symbol</b>	<b>Wert Value</b>				<b>Einh. Unit</b>
		<b>-2</b>	<b>-3</b>	<b>-4</b>	<b>-5</b>	
Fotostrom, $\lambda = 950 \text{ nm}$ Photocurrent $E_e = 0.5 \text{ mW/cm}^2, V_{CE} = 5 \text{ V}$ $E_v = 1000 \text{ lx, Normlicht/standard light A, } V_{CE} = 5 \text{ V}$	$I_{PCE}$ $I_{PCE}$	0.2 ... 0.4 0.95	0.32 ... 0.63 1.5	0.5 ... 1.0 2.3	$\geq 0.8$ 3.6	mA mA
Anstiegszeit/Abfallzeit Rise and fall time $I_C = 1 \text{ mA, } V_{CC} = 5 \text{ V, } R_L = 1 \text{ k}\Omega$	$t_r, t_f$	9	12	15	18	$\mu\text{s}$
Kollektor-Emitter-Sättigungsspannung Collector-emitter saturation voltage $I_C = I_{PCEmin}^{1)} \times 0.3$ $E_e = 0.5 \text{ mW/cm}^2$	$V_{CESat}$	200	200	200	200	mV
Stromverstärkung Current gain $E_e = 0.5 \text{ mW/cm}^2, V_{CE} = 5 \text{ V}$	$\frac{I_{PCE}}{I_{PCB}}$	170	280	420	650	—

<sup>1)</sup>  $I_{PCEmin}$  ist der minimale Fotostrom der jeweiligen Gruppe.

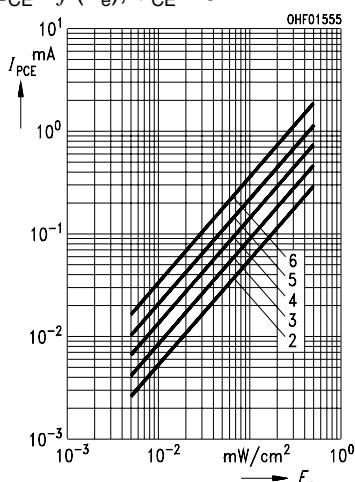
<sup>1)</sup>  $I_{PCEmin}$  is the min. photocurrent of the specified group.

**Relative Spectral Sensitivity**

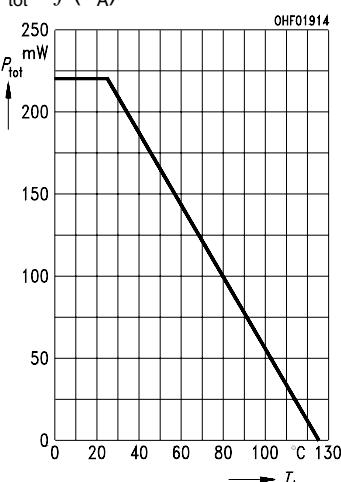
$$S_{\text{rel}} = f(\lambda)$$

**Photocurrent**

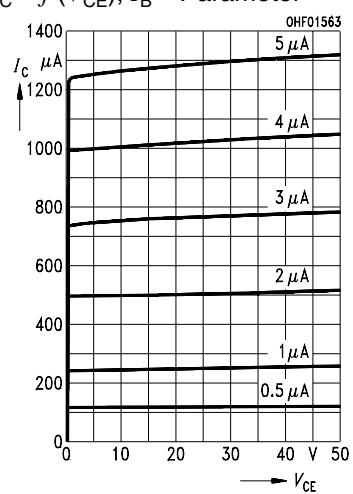
$$I_{\text{PCE}} = f(E_e), V_{\text{CE}} = 5 \text{ V}$$

**Total Power Dissipation**

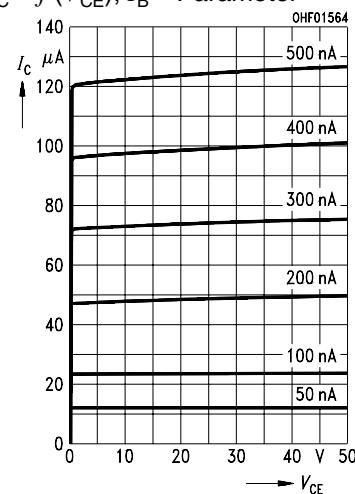
$$P_{\text{tot}} = f(T_A)$$

**Output Characteristics**

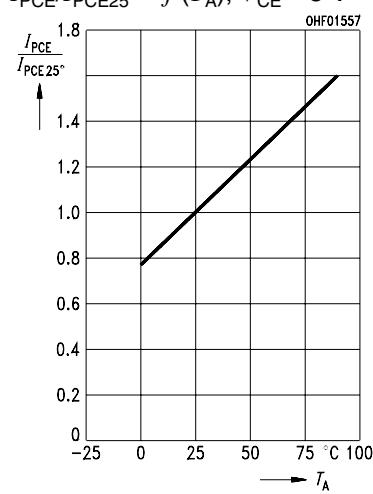
$$I_C = f(V_{\text{CE}}), I_B = \text{Parameter}$$

**Output Characteristics**

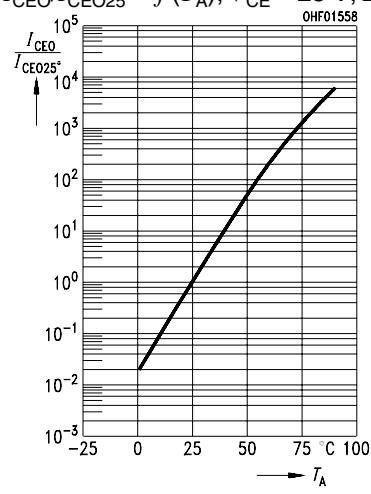
$$I_C = f(V_{\text{CE}}), I_B = \text{Parameter}$$

**Photocurrent**

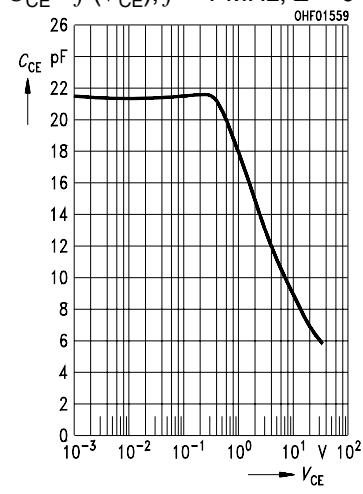
$$I_{\text{PCE}}/I_{\text{PCE}25^{\circ}} = f(T_A), V_{\text{CE}} = 5 \text{ V}$$

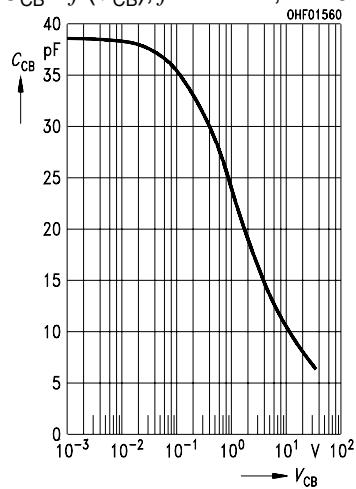
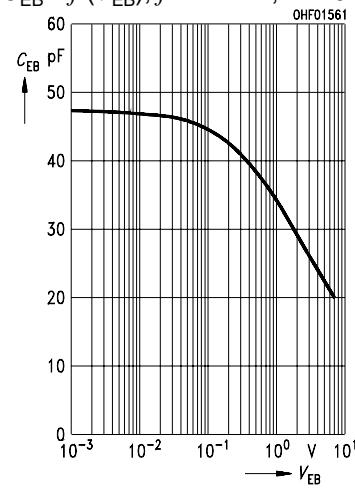
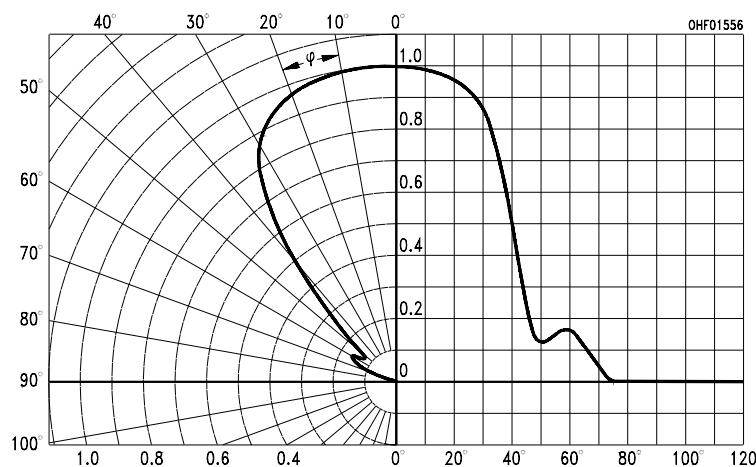
**Dark Current**

$$I_{\text{CEO}}/I_{\text{CEO}25^{\circ}} = f(T_A), V_{\text{CE}} = 25 \text{ V}, E = 0$$

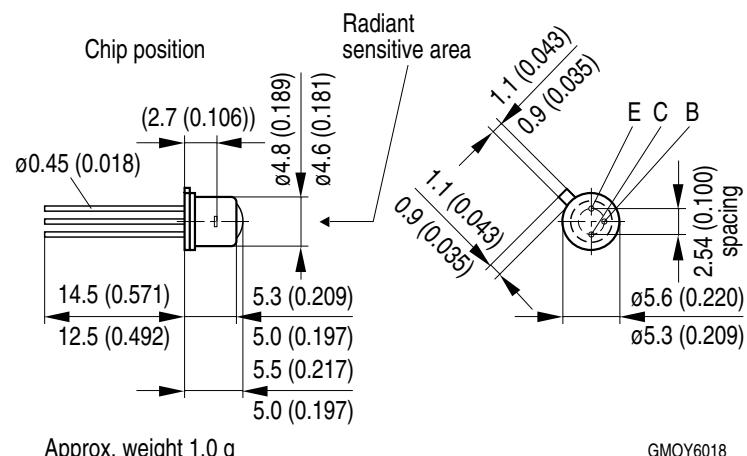
**Collector-Emitter Capacitance**

$$C_{\text{CE}} = f(V_{\text{CE}}), f = 1 \text{ MHz}, E = 0$$



**Collector-Base Capacitance** $C_{CB} = f(V_{CB}), f = 1 \text{ MHz}, E = 0$ **Emitter-Base Capacitance** $C_{EB} = f(V_{EB}), f = 1 \text{ MHz}, E = 0$ **Directional Characteristics** $S_{\text{rel}} = f(\varphi)$ 

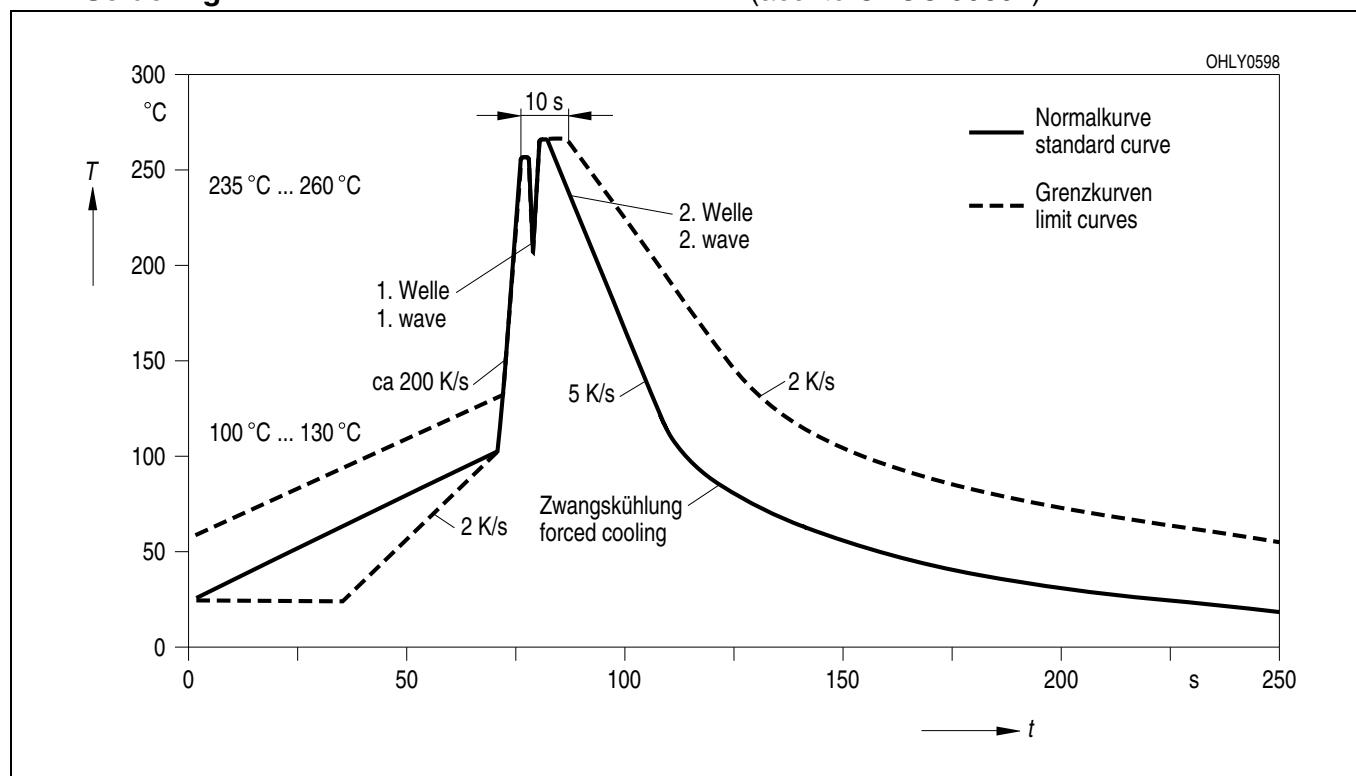
# Maßzeichnung Package Outlines



Maße in mm (inch) / Dimensions in mm (inch).

**Lötbedingungen**  
**Soldering Conditions**  
**Wellenlöten (TTW)**  
**TTW Soldering**

(nach CECC 00802)  
 (acc. to CECC 00802)



Published by  
**OSRAM Opto Semiconductors GmbH**  
 Wernerwerkstrasse 2, D-93049 Regensburg  
[www.osram-os.com](http://www.osram-os.com)  
 © All Rights Reserved.

EU RoHS and China RoHS compliant product



此产品符合欧盟 RoHS 指令的要求；  
 按照中国的相关法规和标准，不含有毒有害物质或元素。

The information describes the type of component and shall not be considered as assured characteristics.  
 Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances. For information on the types in question please contact our Sales Organization.

**Packing**

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

**Components used in life-support devices or systems must be expressly authorized for such purpose!** Critical components<sup>1</sup>, may only be used in life-support devices or systems<sup>2</sup> with the express written approval of OSRAM OS.

<sup>1</sup> A critical component is a component used in a life-support device or system whose failure can reasonably be expected to cause the failure of that life-support device or system, or to affect its safety or effectiveness of that device or system.

<sup>2</sup> Life support devices or systems are intended (a) to be implanted in the human body, or (b) to support and/or maintain and sustain human life. If they fail, it is reasonable to assume that the health of the user may be endangered.